

Wettability and Surface Tension of Molten InGaAs

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Wetting behavior of molten $\text{In}_{0.8}\text{Ga}_{0.2}\text{As}$ on substrates of graphite, BN, SiO_2 , pBN, AlN, SiC and Al_2O_3 and surface tension of molten $\text{In}_{0.8}\text{Ga}_{0.2}\text{As}$ were measured using the growing melt drop method so as to identify a possible crucible material for use in growing crystals.

The relationship of the magnitude of the contact angles between the melts and the substrates was as follows: pBN, BN, graphite > AlN > SiN > SiO_2 > Al_2O_3 , SiC.

The surface tension of $\text{In}_{0.8}\text{Ga}_{0.2}\text{As}$ was $\gamma = 418 \sim 480 \text{ mN/m}$ (at $1100 \sim 1300^\circ\text{C}$)

The effect of roughness of SiO_2 container was investigated from 0.1 to $4 \mu\text{m}$ amplitude of surface. As a result, the molten InGaAs/container wetting behavior was related to the roughness of container.

1. Introduction

The contact angle of ceramic surface with molten materials and surface tension of molten materials is a significant thermophysical properties to be taken into consideration in cases where crucibles for space experiments are designed or when it serves as a tool for analyzing data obtained from such experiments.

InGaAs that was measured this time is paid attention in recent years as a high speed IC and an optoelectronics materials like a laser diode.⁽¹⁾ However, the manufacturing of the ternary compound semiconductor with high uniform monocrystallinity is difficult on the ground. Although the utilizing microgravity environment upon crystal production is conceivable for the detailed characteristic research, no report has been published on the wettabilities of crucible materials with molten InGaAs and Surface tension of molten InGaAs. And that was expected.

In this report, contact angles between molten InGaAs and 8 kinds of crucible material and surface tension of molten InGaAs were measured.

2. Experimental method

Molten sample is $\text{In}_{0.8}\text{Ga}_{0.2}\text{As}$, the melting point is about 1100°C . Crucible materials are SiO_2 , BN, pBN, graphite, AlN, Al_2O_3 , SiC and SiN. Each substrate material is processed in a disk state and has a hole of 0.5mm in diameter at the center and from which the molten sample is pushed out from a lower part to the surface. The shape of disk is 10mm in diameter and 3mm thick.

Figure 1 shows a schematic diagram of the wettability measurement apparatus. A procedure of growing drop is shown in Fig.2.

The image of the liquid drop on a solid substrate is taken with CCD camera and the contour of the liquid drop is extracted with the image processing by a computer. The theoretical contour curve guided from Laplace's equation is made repeated fitting to a contour curve that was obtained, and is calculated a contact angle and surface tension with a final optimal approximation curve.⁽²⁾

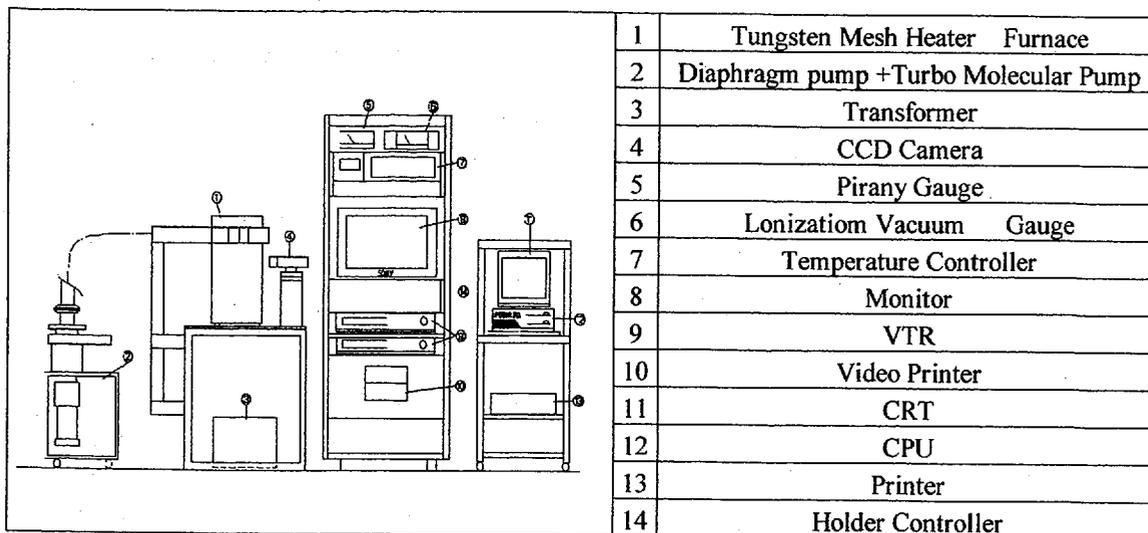


Fig.1 Schematic diagram of Wettability Measurement Unit

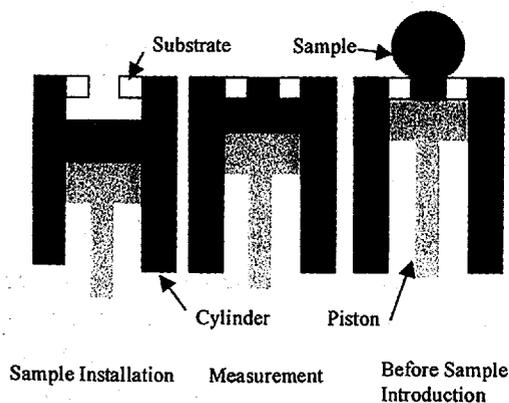


Fig.2 Procedure of the growing drop

Before the experiment the uncertainty in measurement is evaluated by measuring the contact angles of steel sphere. The difference between the theoretical and measured contact angles is within $\pm 1\%$.

The experiment were conducted at temperatures of 1100°C, 1200°C, 1300°C, and in the atmosphere of argon to all substrate materials. The vacuum of the furnace was 2×10^{-4} Torr before introducing argon gas.

3. Experimental results

3.1 The crucible materials effect

Molten InGaAs spouted through a hole of substrates right away, as soon as a top of the melt appeared just above the hole. This phenomenon is observed well repeatedly and the control of liquid

drop formation by the move of a piston was impossible. This might be due to high arsenic dissociation pressures at measurement temperatures. It is conceivable that melt is pushed out from a hole of substrates by this pressure.

Figure 3 shows measurement results of contact angles. Figure 4 is a side view of molten InGaAs drop on substrates.

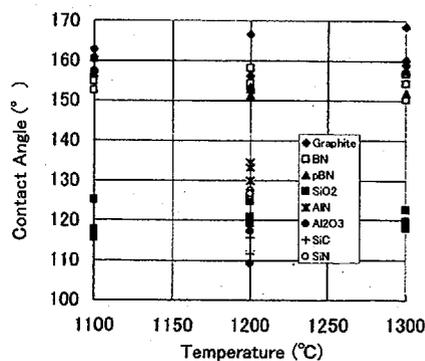
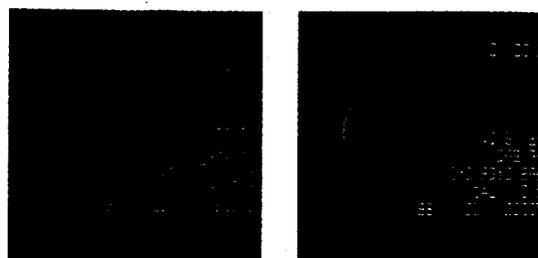


Fig.3 Contact Angle of InGaAs



Substrate : BN
Temperature: 1200°C

Substrate : SiO₂
Temperature: 1200°C

Fig.4 Side view picture of InGaAs drop

Table1 shows measurements data of contact angles. The standard deviation of contact angles is below five degrees. The contact angles with pBN, BN and graphite substrates showed large values, the contact angles with AlN, SiN, SiO₂, Al₂O₃ and SiC substrates showed comparatively small values.

pBN, BN, graphite >> AlN > SiN > SiO₂ > Al₂O₃, SiC

These substrate materials are useful as crucible. Non-wettable characteristics with sample is desirable as crucible materials. The above trend was considered to be suggesting the compatibility of crucible material to molten InGaAs.

Tab.1 Contact Angles of InGaAs (1/2)

Substrate	Temp (°C)	Roughness (μm)	Angle (°)	Sur. Tention (mN/m)	
BN	1100	1.5	156	447	
		1.5	153	424	
		2	155	442	
	1200	1.4	154	428	
		1.4	154	435	
		1.4	158	428	
	1300	1.5	150	460	
		1.5	157	436	
		1.4	154	418	
	pBN	1100	1.2	157	481
			1.4	158	473
			1.1	161	431
1200		1.1	153	457	
		1.1	156	443	
		1.2	151	463	
1300		1.3	158	461	
		1.2	152	492	
		1.4	158	437	
SiO ₂		1100	0.03	118	494
			0.02	125	410
			0.05	117	413
	1200	0.21	119	457	
		0.01	125	459	
		0.06	121	497	
	1300	0.02	123	421	
		0.03	120	431	
		0.11	118	491	
	Graphite	1100	0.3	158	425
			0.3	161	418
			0.4	163	425
1200		0.3	167	414	
		0.4	158	435	
		0.4	156	430	
1300		0.3	169	418	
		0.3	158	482	
		0.4	160	429	

Tab.1 Contact Angles of InGaAs (2/2)

Substrate	Temp (°C)	Roughness (μm)	Angle (°)
AlN	1200	0.07	135
		0.07	133
		0.07	130
Al ₂ O ₃		0.03	109
		0.02	117
		0.03	117
SiC		0.12	112
		0.07	116
		0.08	112
SiN		0.01	128
		0.03	126
		0.05	127

Tab.2 Contact Angle of InGaAs

Substrate	Temp (°C)	Roughness (μm)	Angle (°)
SiO ₂	1200	3.5	160
		3.1	162
		3.8	163
		1.4	159
		0.7	155
		0.73	159
		0.69	153
		0.81	141
		0.20	152
		0.24	156
		0.26	154

3.2 The roughness of container effect

Figure 5 shows measurement results of contact angles. Table.2 shows measurements data of contact angles.

As the roughness of substrates decrease, the contact angle is smaller. The movement of drops on substrates is easy. The rich wettability of substrates with molten InGaAs was considered to cause such movement.

3.3 The measurement of surface tension

Figure 6 shows measurement results of surface tension.

The surface tension of InGaAs was $\gamma = 418 \sim 480 \text{ mN/m}$ (at 1100 ~ 1300 °C). At the same temperature, scattering of results are at almost $\pm 10\%$.

In this experiment, the diameters of drop range from 3 to 4 mm. The drop shape is determined by the balance of gravity and surface tension. The diameters of drop range from 3 to 4 mm shaped in this experiment is very little. Therefore there is no effect of gravity, and scattering of results were brought about.⁽³⁾

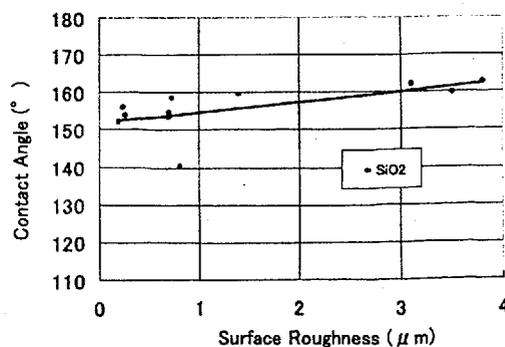


Fig.5 Contact angle vs. roughness of the container surface

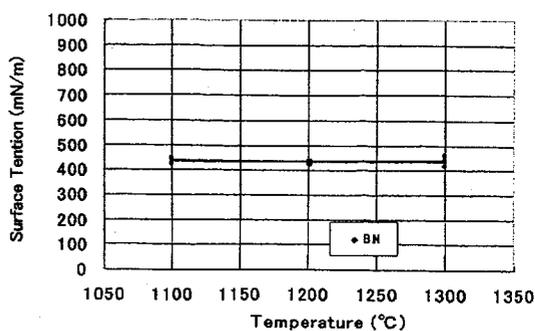


Fig.6 Surface tensions of InGaAs

Conclusion

For the purpose of evaluating compatibility between molten InGaAs and 8 kinds of crucible material, the contact angles were measured by growing drop method in a temperature range between 1100 and 1300°C. The spouting of molten InGaAs through a hole of substrates was observed at the time of the growing drop. This was conceivable that high dissociation pressure of arsenic is a cause.

It understood by the measurement results of contact angles that pBN, BN and graphite are good materials as crucible for InGaAs and that the use of AlN, Al₂O₃, SiC, SiN and SiO₂ must be paid attention.

The relationship between the wettability and the roughness of container was investigated using SiO₂ container. The contact angles are measured by growing drop method increase when surface roughness increase.

The surface tension of molten InGaAs was measured from 1100 to 1300°C.

The surface tension of the molten InGaAs is $\gamma = 418 \sim 480 \text{mN/m}$.

References

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